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NAN YA PLASTICS CORPORATION
ELECTRONIC MATERIALS DIVISION.
COPPER CLAD LAMINATE DEPARTMENT

**Glass cloth base epoxy resin
Flame retardant copper clad laminate**

NO. 201. TUNG HWA N. ROAD,
TAIPEI, TAIWAN.

NP-175TL

■ FEATURES

- Dicy-Free
- Lead-Free Compatible
- Excellent dimensional stability and through-hole reliability
- Superior CAF-Resistance (Anti-migration)
- U.L. file number E98983
- High luminance of multi-functional epoxy contrast with copper for A.O.I
- IPC-4101B/124

■ PERFORMANCE LIST

Characteristics	Unit	Conditioning	Typical Values	SPEC	Test Method
Volume resistivity	MΩ-cm	C-96/35/90	5.0 x10 ⁹	10 ⁶ ↑	2.5.17
Surface resistivity	MΩ	C-96/35/90	5.0 x10 ⁸	10 ⁴ ↑	2.5.17
Permittivity 1 MHZ	-	C-24/23/50	4.3-4.5	5.4 ↓	2.5.5.9
Permittivity 1 GHZ	-	C-24/23/50	3.8-4.0	-	2.5.5.9
Loss Tangent 1 MHZ	-	C-24/23/50	0.016-0.020	0.035 ↓	2.5.5.9
Loss Tangent 1GMHZ	-	C-24/23/50	0.012-0.014	-	2.5.5.9
Arc resistance	SEC	D-48/50+D-0.5/23	120 ↑	60 ↑	2.5.1
Dielectric breakdown	KV	D-48/50	60 ↑	40 ↑	2.5.6
Moisture absorption	%	D-24/23	0.20-0.30	0.35 ↓	2.6.2.1
Flammability	-	C-48/23/50	94V0	94V0	UL94
Peel strength 1 oz	lb/in	288°Cx10" solder floating	8-10	6 ↑	2.4.8
Thermal stress	SEC	288°C solder dipping	600 ↑	10 ↑	2.4.13.1
Glass transition temp	°C	DSC	175 ± 5	150 ↑	2.4.25
Dimensional stability X-Y axis	%	E 4/105	0.01-0.03	0.05 ↓	2.4.39
Coefficient of thermal expansion					
Z-axis before Tg	ppm/°C	TMA	40-60	60 ↓	2.4.24
Z-axis after Tg	ppm/°C	TMA	270-300	300 ↓	
50-260°C	%	TMA	3.5%	3.5% ↓	
T260	min	TMA	>60	30 ↑	2.4.24.1
T288	min	TMA	>20	5 ↑	2.4.24.1
Td (5% Weight Loss)	°C	TGA, 10°C/min	351	325 ↑	-

NOTE:

The average value in the table refers to samples of .020" 1/1.
Test method per IPC-TM-650

Data shown are nominal values for reference only.

■ CONSTRUCTION:

THICKNESS		CONSTRUCTION		THICKNESS		CONSTRUCTION	
mm	mil			mm	mil		
0.05	2	106	1 PLY	0.35	14	7628	2 plies
0.08	3	2112	1PLY	0.38	15	7628	2 plies
0.10	4	1080	2 plies	0.45	18	7628x2+1080x1	
0.11	4	2116	1 ply	0.50	20	7628	3 plies
0.13	5	1080	2 plies	0.53	21	7628	3 plies
0.13sp	5	2116	1 ply	0.60	24	7628	3 plies
0.15	6	1506	1 ply	0.77	31	7628	4 plies
0.16	6	2112	2 plies	0.8	32	7628	4 plies
0.21	8	7628	1 ply	0.9	36	7628	5 plies
0.26	10	2116	2 plies	1.0	39	7628	5 plies
0.30	12	2116	3 plies	1.1	43	7628	6 plies
0.30sp	12	1506	2 plies	1.2	47	7628	6 plies

• 1.2, 1.1, 1.0, 0.9 0.77 mm THICKNESS INCLUDE CLADDING, ALL OTHERS EXCLUDE CLADDING

■ PRODUCT SIZE & THICKNESS

THICKNESS INCH (mm)	COPPER CLADDING		SIZE		THICKNESS TOLERANCE
	OZ (µm)		INCH	mm	
0.004 (0.1)	T (12)	2.0 (70)	48.8 x 36.6	1240 x 0930	IPC-4101B SPEC CLASS C/M
to	H (17)	3.0 (105)	48.8 x 40.5	1240 x 1030	
0.039 (1.0)	1.0 (35)		48.8 x 42.5	1240 x 1080	

■ Keeping the core and prepreg in the same grain direction is crucial to ensure the flatness of multilayer boards.

Grain direction is shown on the Certificate of Conformance.

■ We recommend to evaluate the drilling property.

■ Different oxide treatment may result in variations in the heat resistance properties of the laminates after processing. Pre-production batch runs are recommended to ensure compatibility of materials with chemicals.